

RoHS Compliant

1213-SERIES SFF-8639 RECEPTACLE CONNECTOR

REV	DATE	DESCRIPTION	ECN NO.	NAME
A	15.02.26	PROPOSAL		HSIEN
B	15.12.14	NEW RELEASE		HSIEN

NOTE

1.MATERIAL

HOUSING : HIGE THERMOPLASTIC, UL94V-0,BLACK.
 CAP : HIGE THERMOPLASTIC, UL94V-0,BLACK.
 TERMINAL : COPPER ALLOY,
 BOARD LOCK : COPPER ALLOY,

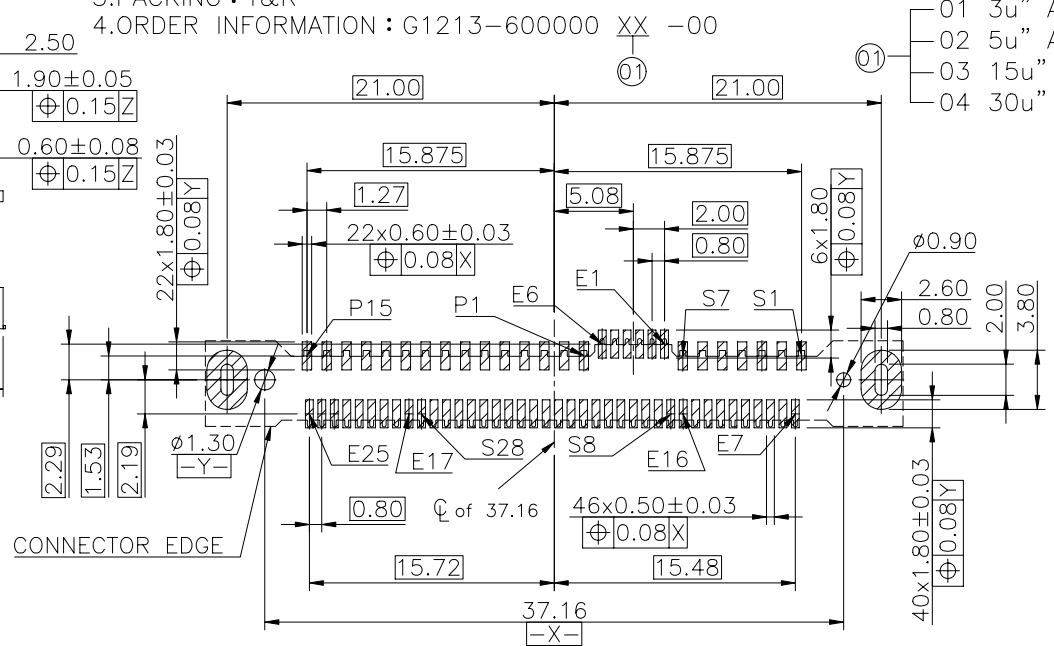
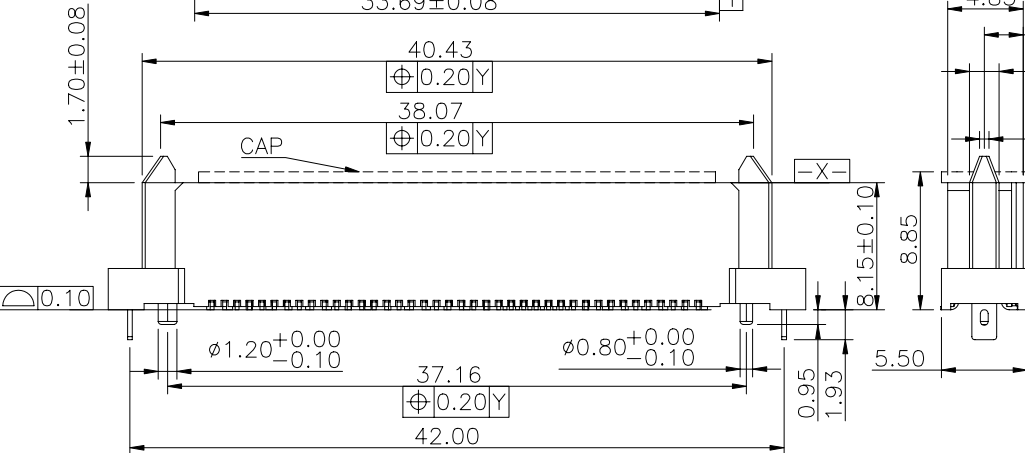
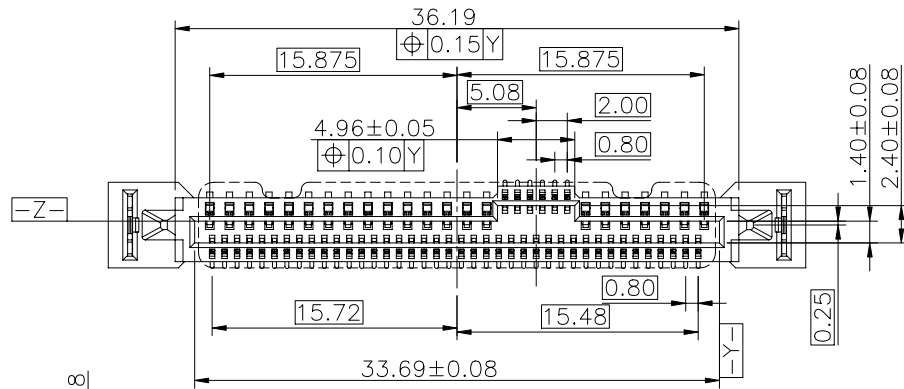
2.PLATING

TERMINAL : SELECTIVE Au ON CONTACT AREA,(SEE ORDER INFORMATION)
 100u" MIN. Sn PLATED ON SOLDER TAIL AREA,
 BOTH OVER 50u" MIN. Ni UNDERPLATED OVERALL.
 BOARD LOCK : 100u" MIN.Sn PLATED ON SOLDER TAIL AREA,
 BOTH OVER 50u" MIN. Ni UNDERPLATED OVERALL.

3.PACKING : T&R

4.ORDER INFORMATION : G1213-600000 XX -00

- 01 3u" Au
- 02 5u" Au
- 03 15u" Au
- 04 30u" Au



RECOMMENDED PCB LAYOUT (TOP VIEW)

PCB THICKNESS:1.6mm

TOLERANCE: ±0.05mm

GENERAL TOLERANCE	WIESON TECHNOLOGIES CO., LTD WIESON	PART NO.:	
X.X = ±0.20	DRAWN BY	HSIEN	G1213-600000XX-00
X.XX = ±0.15	CHECKED BY	FRED LEE	DRAWING NO. G1213-600000XX-00
X.X* = ±3°	APPROVED BY	FRED LEE	DRAWING SIZE 2 : 1 A4
	SORTING NO.	WST	UNIT mm
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